BF256A is a Preferred Device

# **JFET - General Purpose**

# **N-Channel**

N-Channel Junction Field Effect Transistor designed for VHF and UHF applications.

- Low Cost TO-92 Type Package
- Forward Transfer Admittance, Y<sub>fs</sub> = 4.5 mmhos (Min)
- Transfer Capacitance  $C_{rss} = 0.7$  (Typ)
- Power Gain at f = 800 MHz, Typ. = 11 dB

#### **MAXIMUM RATINGS**

| Rating   | Symbol                                     | Value       | Unit        |
|--|--|-------------|-------------|
| Drain-Source Voltage   | V <sub>DS</sub>                            | 30          | Vdc         |
| Drain-Gate Voltage   | V <sub>DG</sub>                            | 30          | Vdc         |
| Gate-Source Voltage  | V <sub>GS</sub>                            | 30          | Vdc         |
| Forward Gate Current   | I <sub>G(f)</sub>                          | 10          | mAdc        |
| Total Device Dissipation  @ T <sub>A</sub> = 25°C  Derate above 25°C | PD   | 360<br>2.88 | mW<br>mW/°C |
| Operating and Storage Channel<br>Temperature Range                   | T <sub>channel</sub> ,<br>T <sub>stg</sub> | -65 to +150 | °C          |

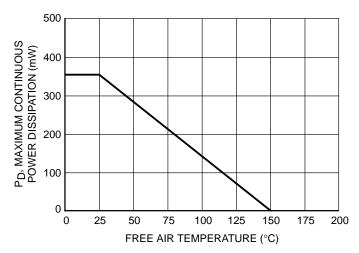
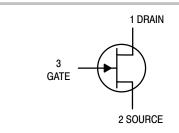


Figure 1. Power Derating Curve



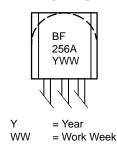
## ON Semiconductor™

#### http://onsemi.com





#### **MARKING DIAGRAMS**



#### **ORDERING INFORMATION**

| Device | Package | Shipping       |  |
|--------|---------|----------------|--|
| BF256A | TO-92   | 5000 Units/Box |  |

**Preferred** devices are recommended choices for future use and best overall value.

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#### **BF256A**

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

| Cha                               | racteristic   | Symbol            | Min | Тур  | Max | Unit  |
|-----------------------------------|---|-------------------|-----|------|-----|-------|
| OFF CHARACTERISTICS               |   |                   |     |      | •   |       |
| Gate-Source Breakdown Voltage     | $(-I_G = -1.0 \mu\text{Adc}, V_{DS} = 0)$                       | −V(BR)GSS         | 30  | _    | _   | Vdc   |
| Gate-Source Voltage               | $(V_{DS} = 15 \text{ Vdc}, I_D = 200 \mu\text{A})$              | -V <sub>G</sub> S | 0.5 | _    | 7.5 | Vdc   |
| Gate Reverse Current              | $(-V_{GS} = 20 \text{ Vdc}, V_{DS} = 0)$                        | -I <sub>GSS</sub> | _   | _    | 5.0 | nAdc  |
| ON CHARACTERISTICS                |   |                   |     |      |     |       |
| Zero-Gate-Voltage Drain Current ( | Note 1.) $(V_{DS} = 15 \text{ Vdc}, V_{GS} = 0)$                | IDSS              | 3.0 | -    | 7.0 | mAdc  |
| SMALL-SIGNAL CHARACTER            | RISTICS   | •                 | •   | •    | -   | •     |
| Forward Transfer Admittance       | (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0, f = 1 kHz)      | Y <sub>fs</sub>   | 4.5 | 5.0  | _   | mmhos |
| Reverse Transfer Capacitance      | (V <sub>DS</sub> = 20 Vdc, -V <sub>GS</sub> = 1 Vdc, f = 1 MHz) | C <sub>rss</sub>  | _   | 0.7  | _   | pF    |
| Output Capacitance                | (V <sub>DS</sub> = 20 Vdc, V <sub>GS</sub> = 0, f = 1 MHz)      | C <sub>oss</sub>  | _   | 1.0  | -   | pF    |
| Cut-Off Frequency (Note 2.)       | (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0)                 | fgfs              | _   | 1000 | _   | MHz   |

<sup>1.</sup> Pulse Test: Pulse Width =  $300 \mu s$ , Duty Cycle = 2.0%.

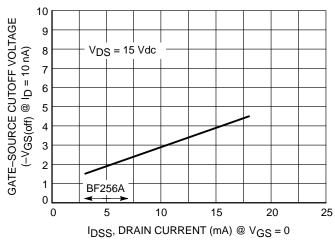


Figure 2. Correlation Between –VGS(off) and IDSS

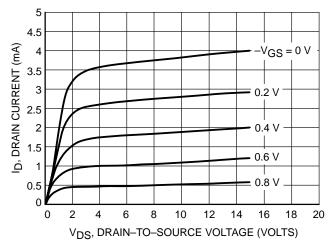


Figure 3. Drain Current versus Drain-to-Source Voltage

<sup>2.</sup> The frequency at which gfs is 0.7 of its value at 1 KHz.

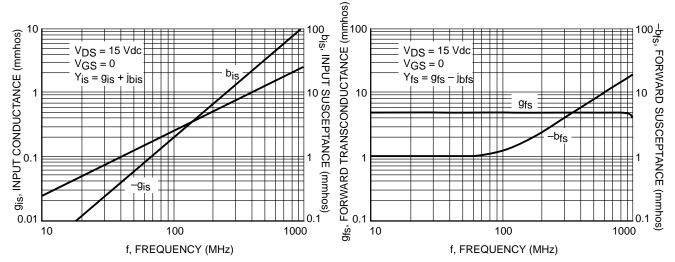


Figure 4. Input Admittance versus Frequency

Figure 5. Forward Transfer Admittance versus Frequency

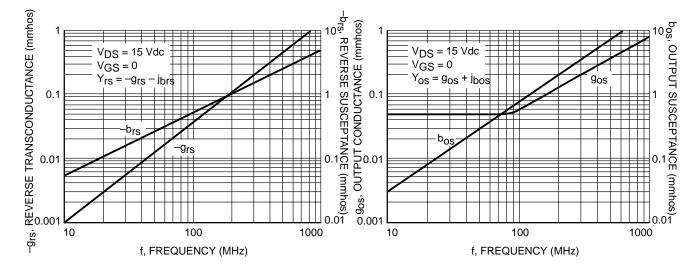


Figure 6. Reverse Transfer Admittance versus Frequency

Figure 7. Output Admittance versus Frequency

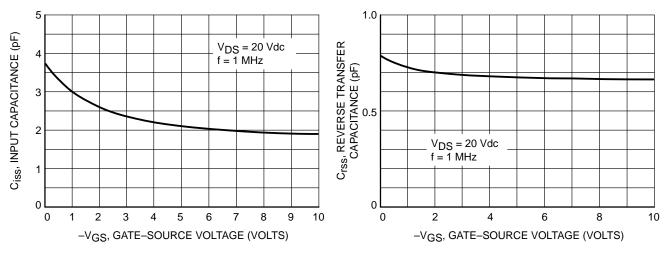


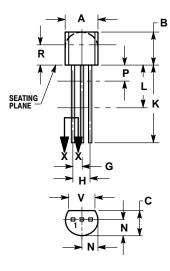
Figure 8. Input Capacitance versus Gate-Source Voltage

Figure 9. Reverse Transfer Capacitance versus Gate-Source Voltage

#### **BF256A**

#### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AL** 





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

|     | INCHES |       | MILLIMETERS |       |
|-----|--------|-------|-------------|-------|
| DIM | MIN    | MAX   | MIN         | MAX   |
| Α   | 0.175  | 0.205 | 4.45        | 5.20  |
| В   | 0.170  | 0.210 | 4.32        | 5.33  |
| C   | 0.125  | 0.165 | 3.18        | 4.19  |
| D   | 0.016  | 0.021 | 0.407       | 0.533 |
| G   | 0.045  | 0.055 | 1.15        | 1.39  |
| Н   | 0.095  | 0.105 | 2.42        | 2.66  |
| 7   | 0.015  | 0.020 | 0.39        | 0.50  |
| K   | 0.500  |       | 12.70       |       |
| L   | 0.250  |       | 6.35        |       |
| N   | 0.080  | 0.105 | 2.04        | 2.66  |
| P   |        | 0.100 |             | 2.54  |
| R   | 0.115  |       | 2.93        |       |
| ٧   | 0.135  |       | 3.43        |       |

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